

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-24 (canceled)

Claim 25 (currently amended): A multilayer printed circuit board comprising:

a resin substrate having a first surface and a second surface;

a first resin insulating layer formed over at least one of the first and second surfaces of the resin substrate, the first resin insulating layer comprising a thermosetting polyolefin resin;

a lower metal layer formed on the first resin insulating layer ~~and being flat and level~~;
and

a conductor circuit comprising a metal and formed on the lower metal layer,

wherein said lower metal layer has a same pattern as said conductor circuit and comprises at least one metal selected from the group consisting of metals of the 4th through 7th periods in Group 4A through Group 1B of the long-form periodic table of the elements, Al, and Sn, excluding Cu, and said first resin insulating layer has a flat and level surface such that the lower metal layer formed on said flat and level surface of said first resin insulating layer is made sufficiently flat and level and said conductor circuit formed on said lower metal layer is made sufficiently flat to provide no signal conduction delay for a high frequency signal.

Claim 26 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said lower metal comprises at least one metal selected from the group consisting of Al, Fe, W, Mo, Sn, Ni, Co, Cr, Ti and noble metals.

Claims 27-28 (canceled)

Claim 29 (currently amended): The multilayer printed circuit board according to Claim 25, wherein said flat and level surface of said first resin insulating layer ~~has a surface~~ is obtained by plasma treatment or corona discharge treatment.

Claim 30 (previously presented): The multilayer printed circuit board according to Claim 25, further comprising an upper metal layer on said conductor circuit, wherein said upper metal layer comprises at least one metal selected from the group consisting of metals of the 4th through 7th periods in Group 4A through Group IB of the long-form periodic table of the elements, Al, and Sn, excluding Cu and has a second resin insulating layer or a solder resist layer thereon.

Claim 31 (previously presented): The multilayer printed circuit board according to Claim 25, further comprising a layer made of Cu interposed between the said lower metal layer and said conductor circuit.

Claim 32 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said lower metal layer has a thickness in a range of 0.01 to 0.2 μm .

Claims 33-63 (canceled)

Claim 64 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said lower metal layer is formed by plating, physical vapor deposition or chemical vapor deposition.

Claim 65 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said thermosetting polyolefin resin has a dielectric constant value of not more than 3 and a dielectric loss tangent value of not more than 0.05.

Claim 66 (canceled)

Claim 67 (previously presented): The multilayer printed circuit board according to Claim 25, wherein the first resin insulating layer, the lower metal layer on said first resin insulating layer and the conductor circuit on said lower metal layer comprise a unit and said unit is formed in a successive series on said resin substrate.

Claim 68 (previously presented): The multilayer printed circuit board according to Claim 30, further comprising another lower metal layer on said second resin insulating layer, and another conductor circuit made of a metal on said another lower metal layer.

Claim 69 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said resin substrate comprises a copper-clad laminate, and has a buildup structure on said first and second surfaces of said resin substrate.

Claim 70 (previously presented): The multilayer printed circuit board according to Claim 30, wherein said upper metal layer covers said conductor circuit entirely.

Claim 71 (previously presented): The multilayer printed circuit board according to Claim 25, wherein said first and second surfaces of said resin substrate have said first resin insulating layer, said lower metal layer and said conductor circuit formed thereon.